

FPF1007-FPF1009 IntelliMAX™ Advanced Load Products

Features

- 1.2 to 5.5 V Input Voltage Range
- Typical $R_{ON} = 30\text{ m}\Omega$ at $V_{IN} = 5.5\text{ V}$
- Typical $R_{ON} = 40\text{ m}\Omega$ at $V_{IN} = 3.3\text{ V}$
- Fixed Three Different Turn-on Rise Time $10\text{ }\mu\text{s} / 80\text{ }\mu\text{s} / 1\text{ ms}$
- Low $< 10\text{ }\mu\text{A}$ at $V_{IN} = 3.3\text{ V}$ Quiescent Current
- Internal ON Pin Pull Down
- Output Discharge Function
- ESD Protection above 8000 V HBM and 2000 V CDM
- RoHS Compliant

Applications

- PDAs
- Cell Phones
- GPS Devices
- MP3 Players
- Digital Cameras
- Peripheral Ports
- Hot-Swap Supplies
- Notebook Computers



General Description

The FPF1007/8/9 are low R_{DS} P-Channel MOSFET load switches offered in a selection of $10\text{ }\mu\text{s}$, $80\text{ }\mu\text{s}$, and 1 ms slew rate turn-on options for transient / in-rush current control. To support trends in mobile application requirements, the minimum operating input voltage has been reduced down to 1.2 V , the input current leakage has been minimized to extend battery life, and the ESD-protection has been designed to withstand a minimum of 8 kV (HBM) and 2 kV (CDM).

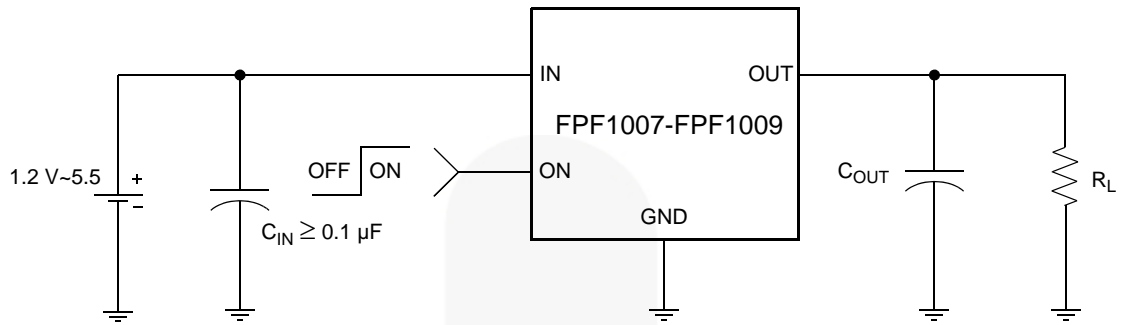
The switch is controlled by an active-high logic input (ON pin), allowing direct interface with a low-voltage control signal. An internal ON pin pull-down resistor protects against unintentional device turn-on in the initial state. An on-chip pull-down resistor on the output is enabled when the switch is turned-off and provides quick, robust discharge of the output load.



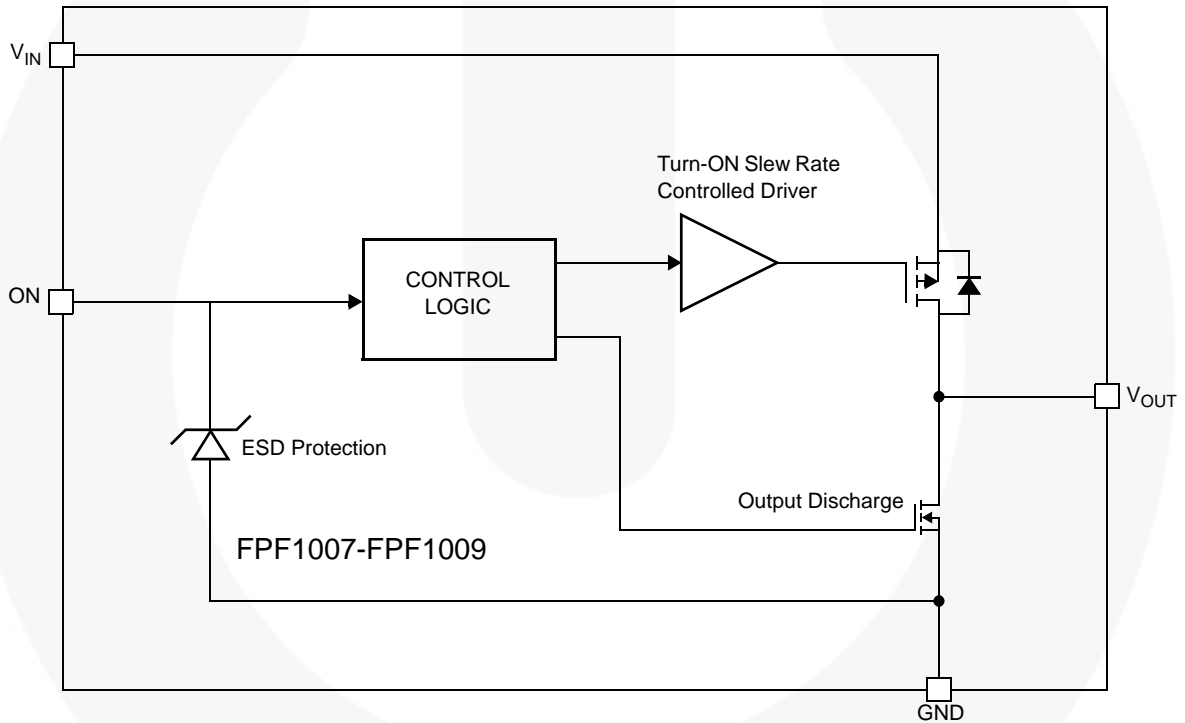
Ordering Information

| Part | Switch R_{ON} at 5.5 V [Typ.] | Rise Time [Typ.] | Output Discharge [Typ.] | ON Pin Activity |
|---------|---------------------------------|-------------------------|-------------------------|-----------------|
| FPF1007 | $30\text{ m}\Omega$, PMOS | $10\text{ }\mu\text{s}$ | $60\text{ }\Omega$ | Active HIGH |
| FPF1008 | $30\text{ m}\Omega$, PMOS | $80\text{ }\mu\text{s}$ | $60\text{ }\Omega$ | Active HIGH |
| FPF1009 | $30\text{ m}\Omega$, PMOS | 1 ms | $60\text{ }\Omega$ | Active HIGH |

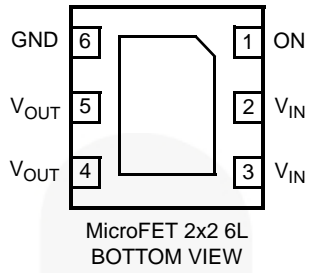
Typical Application Circuit



Functional Block Diagram



Pin Configuration



Pin Description

| Pin | Name | Function |
|------|------------------|---|
| 4, 5 | V _{OUT} | Switch Output: Output of the power switch |
| 2, 3 | V _{IN} | Supply Input: Input to the power switch and the supply voltage for the IC |
| 6 | GND | Ground |
| 1 | ON | ON/OFF Control Input |

Absolute Maximum Ratings

| Parameter | Min. | Max. | Unit |
|---|------|------|--------------------|
| V_{IN} , V_{OUT} , ON to GND | -0.3 | 6.0 | V |
| Maximum Continuous Switch Current | | 1.5 | A |
| Power Dissipation at $T_A = 25^\circ\text{C}^{(1)}$ | | 1.2 | W |
| Storage Junction Temperature | -65 | +150 | $^\circ\text{C}$ |
| Operating Temperature Range | -40 | +85 | $^\circ\text{C}$ |
| Thermal Resistance, Junction to Ambient | | 86 | $^\circ\text{C/W}$ |
| Electrostatic Discharge Protection | HBM | 8000 | V |
| | CDM | 2000 | V |

Note:

Package power dissipation on 1-square inch pad, 2 oz. copper board.

Recommended Operating Range

| Parameter | Min. | Max. | Unit |
|--------------------------------------|------|------|------------------|
| V_{IN} | 1.2 | 5.5 | V |
| Ambient Operating Temperature, T_A | -40 | +85 | $^\circ\text{C}$ |

Electrical Characteristics

$V_{IN} = 1.2\text{ V to } 5.5\text{ V}$, $T_A = -40\text{ to } +85^\circ\text{C}$ unless otherwise noted. Typical values are at $V_{IN} = 3.3\text{ V}$ and $T_A = 25^\circ\text{C}$.

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Units |
|-----------------------------|----------------------|---|------|------|------|------------------|
| Basic Operation | | | | | | |
| Operating Voltage | V_{IN} | | 1.2 | | 5.5 | V |
| Quiescent Current | I_Q | $I_{OUT} = 0\text{ mA}$, $V_{IN} = 3.3\text{ V}$, $V_{ON} = \text{Enabled}$ | | 8 | | μA |
| | | $I_{OUT} = 0\text{ mA}$, $V_{IN} = 5.5\text{ V}$, $V_{ON} = \text{Enabled}$ | | | 15 | |
| Off Supply Current | $I_{Q(\text{off})}$ | $V_{ON} = \text{GND}$, $V_{OUT} = \text{OPEN}$ | | | 1 | μA |
| Off Switch Current | $I_{SD(\text{off})}$ | $V_{ON} = \text{GND}$, $V_{OUT} = \text{GND}$ | | 0.1 | 1.0 | μA |
| On-Resistance | R_{ON} | $V_{IN} = 5.5\text{ V}$, $I_{OUT} = 200\text{ mA}$, $T_A = 25^\circ\text{C}$ | | 30 | 40 | $\text{m}\Omega$ |
| | | $V_{IN} = 3.3\text{ V}$, $I_{OUT} = 200\text{ mA}$, $T_A = 25^\circ\text{C}$ | | 40 | 55 | |
| | | $V_{IN} = 1.5\text{ V}$, $I_{OUT} = 200\text{ mA}$, $T_A = 25^\circ\text{C}$ | | 100 | 130 | |
| | | $V_{IN} = 1.2\text{ V}$, $I_{OUT} = 200\text{ mA}$, $T_A = 25^\circ\text{C}$ | | 175 | 250 | |
| | | $V_{IN} = 3.3\text{ V}$, $I_{OUT} = 200\text{ mA}$, $T_A = -40^\circ\text{C to } +85^\circ\text{C}$ | 20 | | 65 | |
| Output Pull Down Resistance | R_{PD} | $V_{IN} = 3.3\text{ V}$, $V_{ON} = 0\text{ V}$, $T_A = 25^\circ\text{C}$ | | 60 | | Ω |
| ON Input Logic Low Voltage | V_{IL} | $V_{IN} = 1.2\text{ V to } 5.5\text{ V}$ | | | 0.4 | V |
| ON Input Logic High Voltage | V_{IH} | $V_{IN} = 1.2\text{ V to } 5.5\text{ V}$ | 1 | | | V |
| ON Input Leakage (On) | | $V_{ON} = V_{IN} = 5.5\text{ V}$ | | | 10 | μA |
| ON Input Leakage (Off) | | $V_{ON} = \text{GND}$ | | | 1 | μA |
| Dynamic | | | | | | |
| FPF1007 | | | | | | |
| Turn On | t_{ON} | $V_{IN} = 3.3\text{ V}$, $R_L = 500\ \Omega$, $R_{L_CHIP} = 60\ \Omega$, $C_{OUT} = 0.1\ \mu\text{F}$, $T_A = 25^\circ\text{C}$ | | 12 | | μs |
| Rise Time | t_R | | | 10 | | μs |
| Turn Off | t_{OFF} | | | 40 | | μs |
| Fall Time | t_F | | | 15 | | μs |
| FPF1008 | | | | | | |
| Turn On | t_{ON} | $V_{IN} = 3.3\text{ V}$, $R_L = 500\ \Omega$, $R_{L_CHIP} = 60\ \Omega$, $C_{OUT} = 0.1\ \mu\text{F}$, $T_A = 25^\circ\text{C}$ | | 125 | | μs |
| Rise Time | t_R | | | 80 | | μs |
| Turn Off | t_{OFF} | | | 40 | | μs |
| Fall Time | t_F | | | 15 | | μs |
| FPF1009 | | | | | | |
| Turn On | t_{ON} | $V_{IN} = 3.3\text{ V}$, $R_L = 500\ \Omega$, $R_{L_CHIP} = 60\ \Omega$, $C_{OUT} = 0.1\ \mu\text{F}$, $T_A = 25^\circ\text{C}$ | | 2 | | ms |
| Rise Time | t_R | | | 1 | | ms |
| Turn Off | t_{OFF} | | | 40 | | μs |
| Fall Time | t_F | | | 15 | | μs |

Typical Characteristics

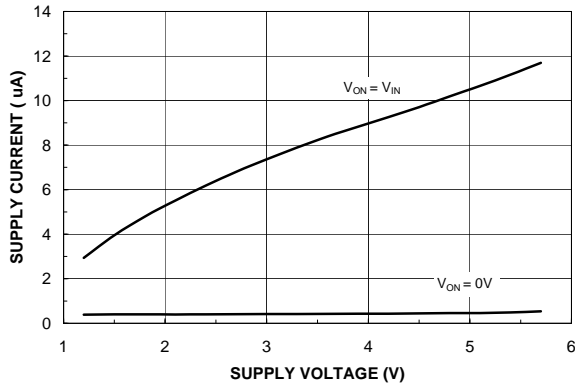


Figure 1. Quiescent Current vs. Input Voltage

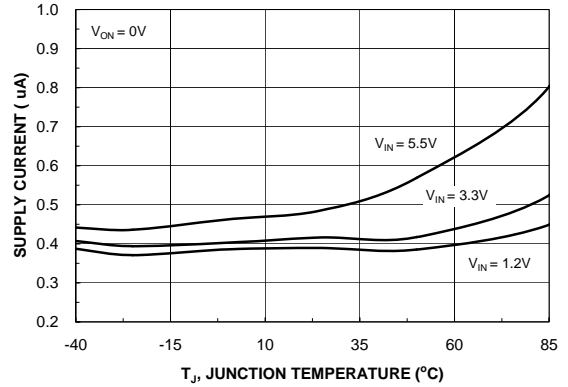


Figure 2. Quiescent Current vs. Temperature

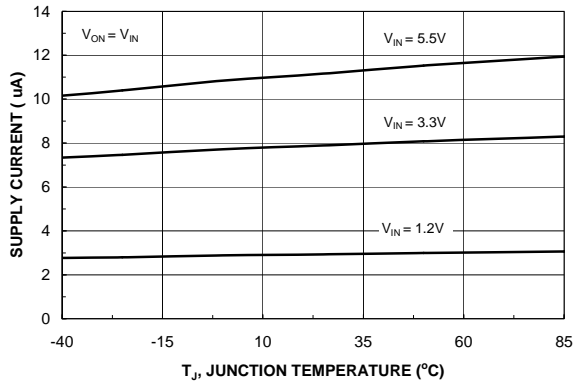


Figure 3. Quiescent Current vs. Temperature

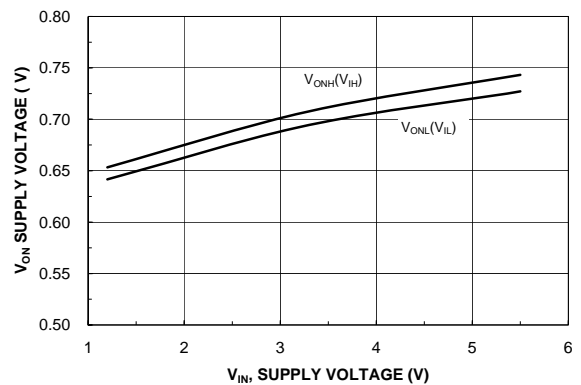


Figure 4. V_{ON} Voltage vs. Input Voltage

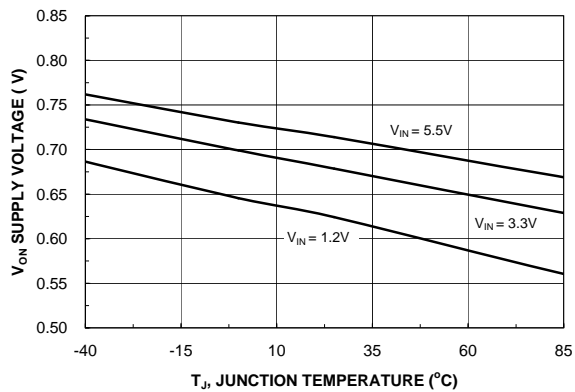


Figure 5. V_{ON} Low Voltage vs. Temperature

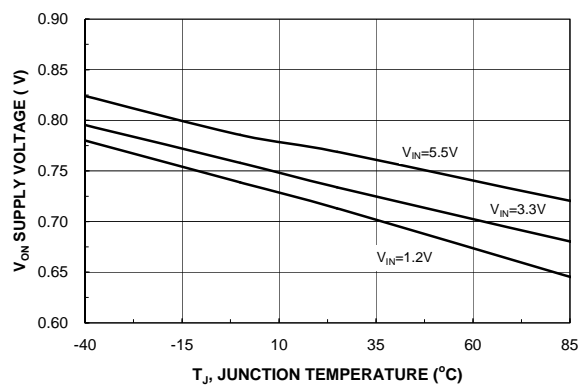


Figure 6. V_{ON} High Voltage vs. Temperature

Typical Characteristics

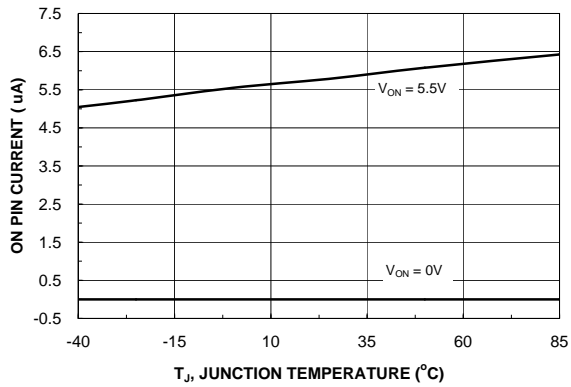


Figure 7. On Pin Current vs. Temperature

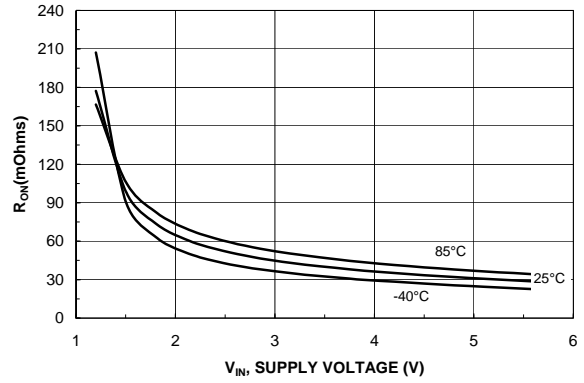


Figure 8. R_{ON} vs. V_{IN}

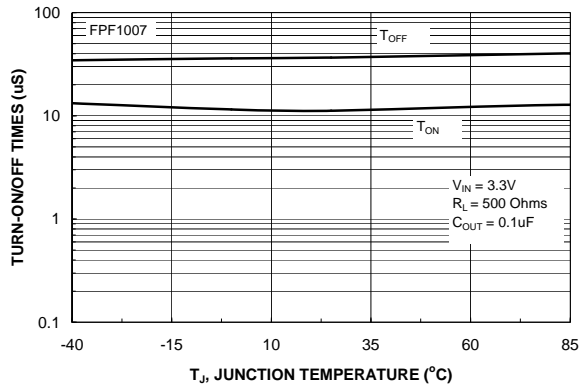


Figure 9. FPF1007 t_{ON} / t_{OFF} vs. Temperature

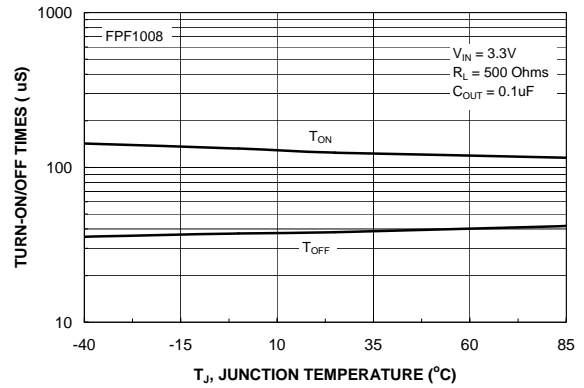


Figure 10. FPF1008 t_{ON} / t_{OFF} vs. Temperature

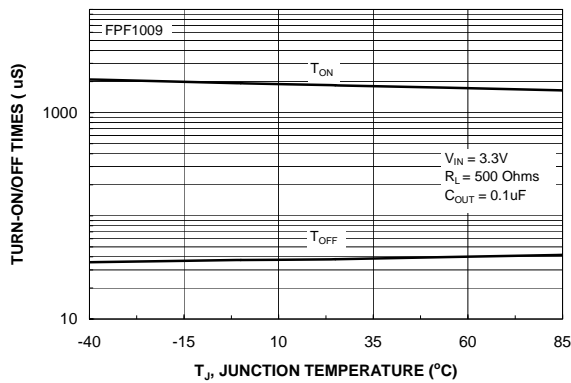


Figure 11. FPF1009 t_{ON} / t_{OFF} vs. Temperature

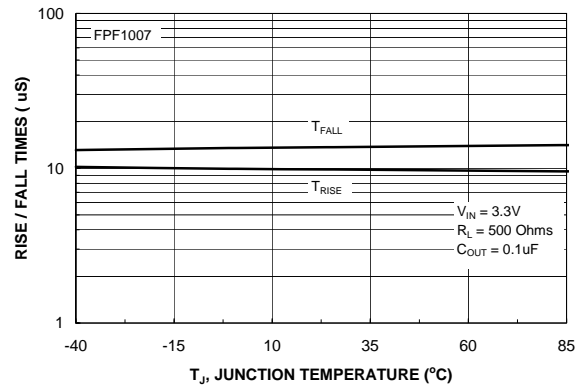


Figure 12. FPF1007 t_{RISE} / t_{FALL} vs. Temperature

Typical Characteristics

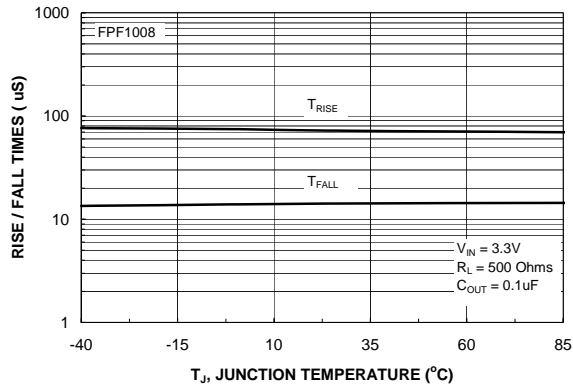


Figure 13. FPF1008 t_{RISE} / t_{FALL} vs. Temperature

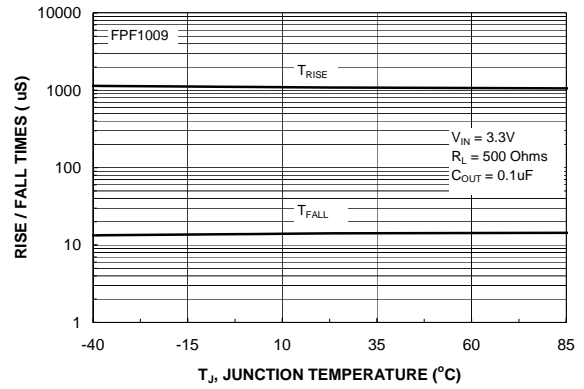


Figure 14. FPF1009 t_{RISE} / t_{FALL} vs. Temperature

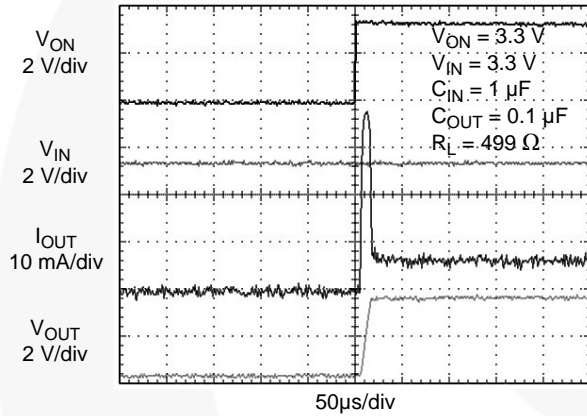


Figure 15. FPF1007 Turn-On Response

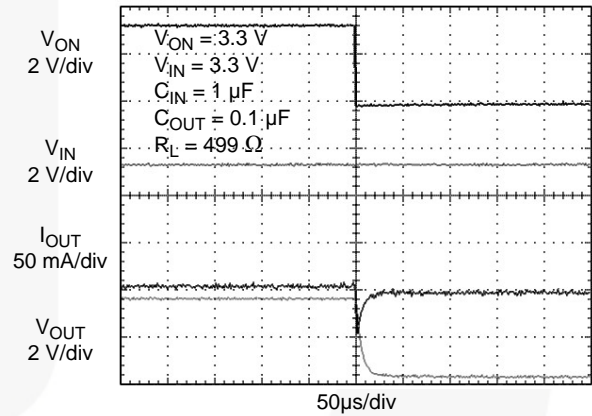


Figure 16. FPF1007 Turn-Off Response
Load current discharged through on-chip output discharge resistor

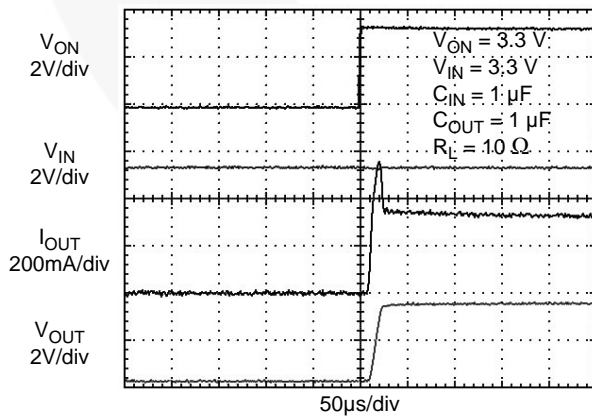


Figure 17. FPF1007 Turn-On Response (C_{OUT} = 1 μF)

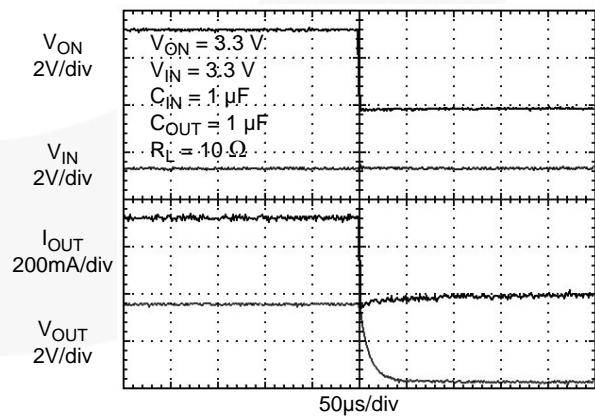


Figure 18. FPF1007 Turn-Off Response

Typical Characteristics

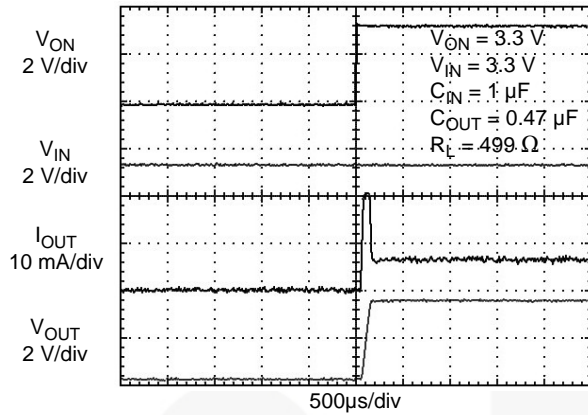


Figure 19. FPF1008 Turn-On Response

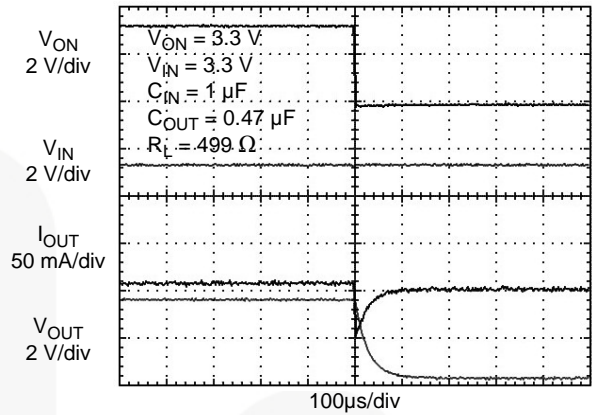


Figure 20. FPF1008 Turn-Off Response
Load current discharged through on-chip output discharge resistor

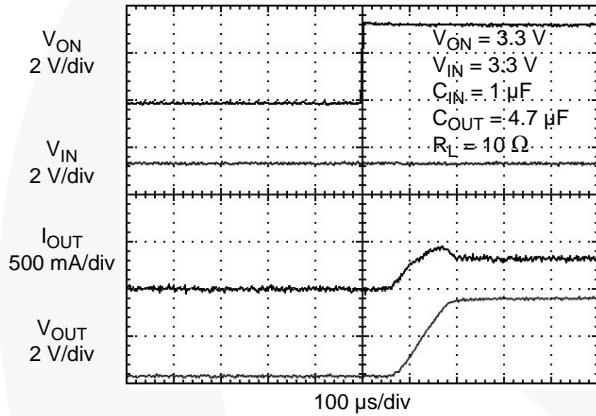


Figure 21. FPF1008 Turn-On Response ($C_{OUT} = 4.7\text{ }\mu\text{F}$)

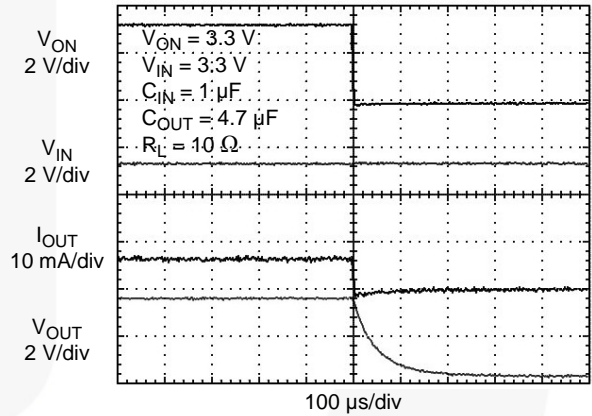


Figure 22. FPF1008 Turn-Off Response

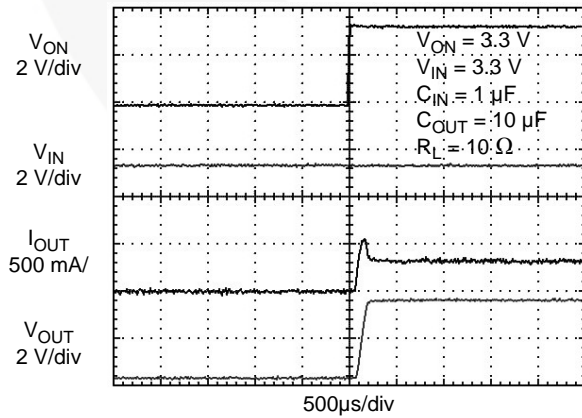


Figure 23. FPF1008 Turn-On Response ($C_{OUT} = 10\text{ }\mu\text{F}$)

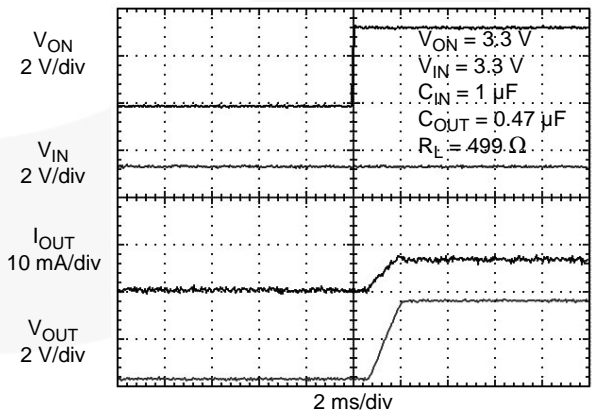


Figure 24. FPF1009 Turn-On Response

Typical Characteristics

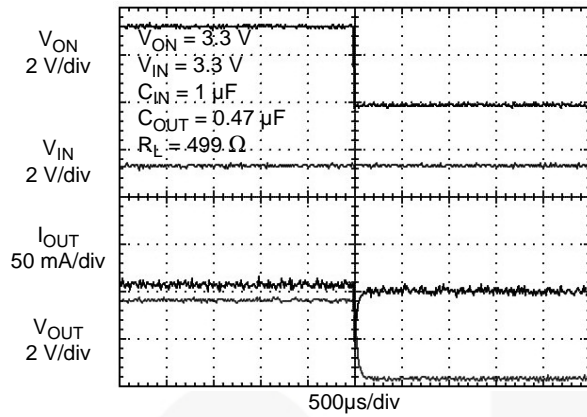


Figure 25. FPF1009 Turn-Off Response
Load current discharged through on-chip output discharge resistor

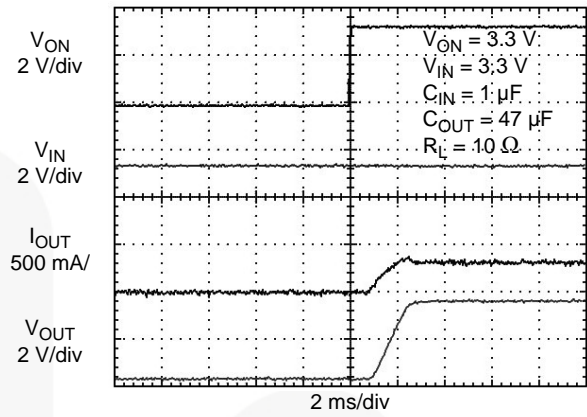


Figure 26. FPF1009 Turn-On Response ($C_{OUT} = 47 \mu F$)

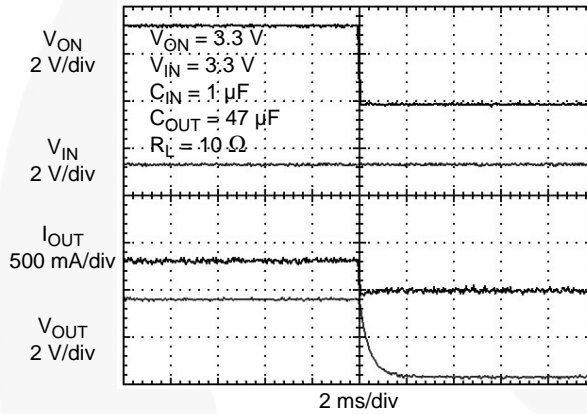


Figure 27. FPF1009 Turn-Off Response

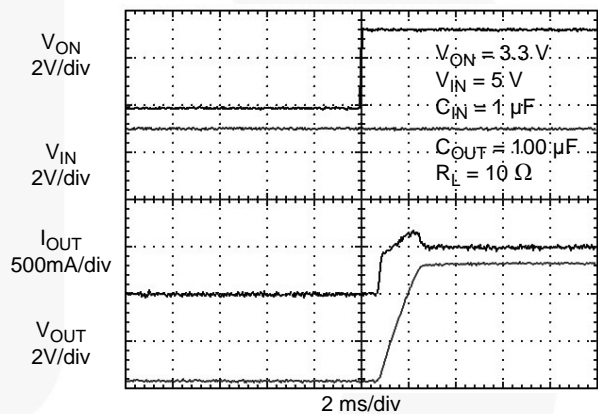
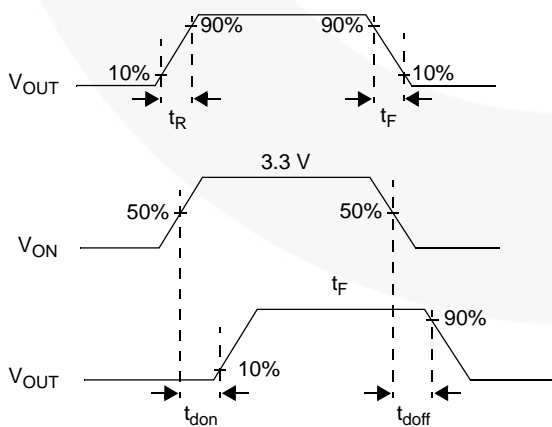


Figure 28. FPF1009 Turn-On Response
($C_{OUT} = 100 \mu F$, $V_{IN} = 5 V$)

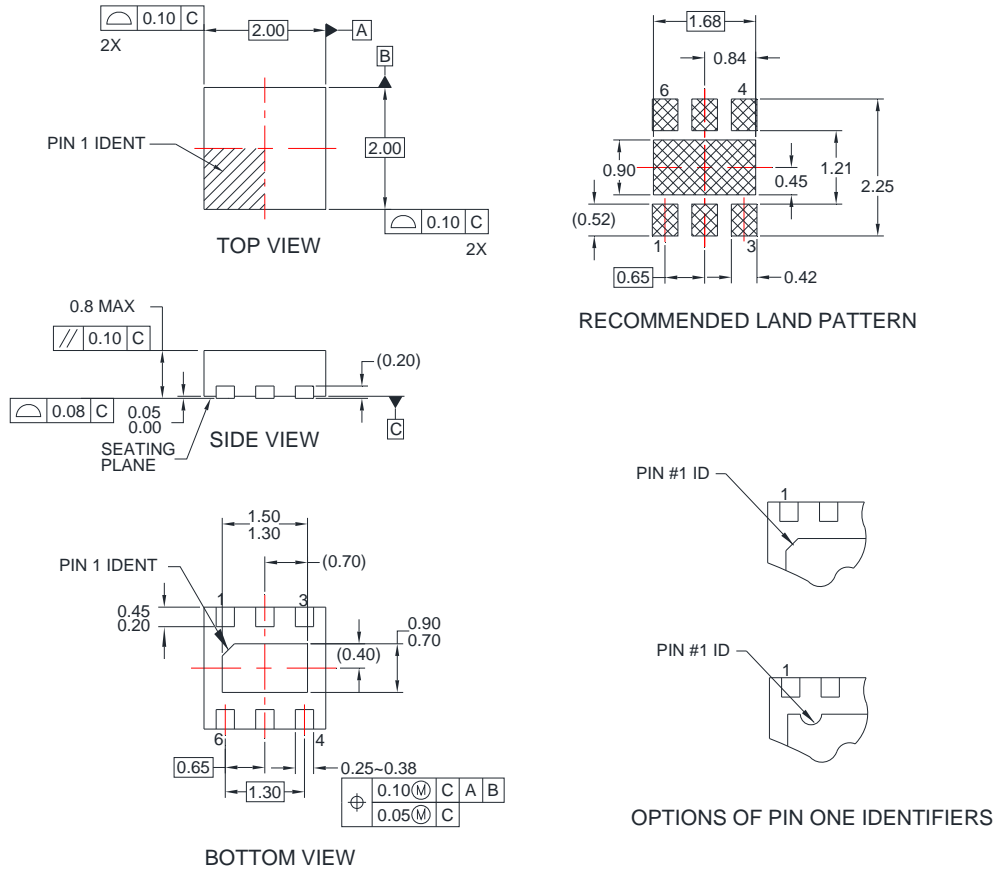
Timing Diagram



where:

- t_{ON} = Turn-On Time
- t_{OFF} = Turn-Off Time
- t_{don} = Turn-On Delay Time
- t_{doff} = Turn-Off Delay Time
- t_R = Rise Time
- t_F = V_{OUT} Fall Time
- $t_{ON} = t_R + t_{don}$
- $t_{OFF} = t_F + t_{doff}$

Dimensional Outline and Pad Layout



NOTES:

- A. DOES NOT FULLY CONFORM TO JEDEC REGISTRATION, MO-229.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- D. LANDPATTERN RECOMMENDATION IS BASED ON FSC DESIGN ONLY
- E. DRAWING FILENAME: MKT-MLP06Krev3.

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PRODUCT STATUS DEFINITIONS

Definition of Terms

| Datasheet Identification | Product Status | Definition |
|--------------------------|-----------------------|---|
| Advance Information | Formative / In Design | Datasheet contains the design specifications for product development. Specifications may change in any manner without notice. |
| Preliminary | First Production | Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design. |
| No Identification Needed | Full Production | Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design. |
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